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Vishay Siliconix

Automotive P-Channel 100 V (D-S) 175 °C MOSFET

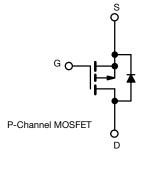
| PRODUCT SUMMARY | | | | | | |
|--|--------|--|--|--|--|--|
| V _{DS} (V) | -100 | | | | | |
| $R_{DS(on)}(\Omega)$ at $V_{GS} = -10 \text{ V}$ | 0.0190 | | | | | |
| $R_{DS(on)}$ (Ω) at V_{GS} = -4.5 V | 0.0222 | | | | | |
| I _D (A) | -93 | | | | | |
| Configuration | Single | | | | | |
| Package | TO-263 | | | | | |

FEATURES

- TrenchFET® power MOSFET
- Package with low thermal resistance
- 100 % R_q and UIS tested
- AEC-Q101 qualified d
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>







| ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted) | | | | | | |
|--|-------------------------|-----------------------------------|-------------|------|--|--|
| PARAMETER | SYMBOL | LIMIT | UNIT | | | |
| Drain-Source Voltage | V_{DS} | -100 | V | | | |
| Gate-Source Voltage | V _{GS} | ± 20 | | | | |
| Continuous Drain Current | T _C = 25 °C | 1 | -93 | | | |
| Continuous Drain Current | T _C = 125 °C | l _D | -53 | | | |
| Continuous Source Current (Diode Conduct | I _S | -120 | А | | | |
| Pulsed Drain Current ^b | I _{DM} | -200 | | | | |
| Single Pulse Avalanche Current | L = 0.1 mH | I _{AS} | -70 | | | |
| Single Pulse Avalanche Energy | L=0.1111H | E _{AS} | 245 | mJ | | |
| Maximum Power Dissipation b | T _C = 25 °C | P _D | 375 | W | | |
| waximum rower dissipation 5 | T _C = 125 °C | | 125 | Į VV | | |
| Operating Junction and Storage Temperature Range | | T _J , T _{stg} | -55 to +175 | °C | | |

| THERMAL RESISTANCE RATINGS | | | | | | |
|----------------------------|-------------|------------|-------|------|--|--|
| PARAMETER | | SYMBOL | LIMIT | UNIT | | |
| Junction-to-Ambient | PCB Mount c | R_{thJA} | 40 | °C/W | | |
| Junction-to-Case (Drain) | Prain) | | 0.4 | C/VV | | |

Notes

- a. Package limited.
- b. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.
- c. When mounted on 1" square PCB (FR4 material).
- d. Parametric verification ongoing.

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| PARAMETER | SYMBOL | TEST CONDITIONS | | MIN. | TYP. | MAX. | UNIT |
|--------------------------------------|-------------------------|--|---|------|--------|--------|------|
| Static | | - | | | • | | |
| Drain-Source Breakdown Voltage | V _{DS} | $V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$ | | -100 | - | - | V |
| Gate-Source Threshold Voltage | V _{GS(th)} | V _{DS} = | $V_{DS} = V_{GS}, I_{D} = -250 \ \mu A$ | | -2.0 | -2.5 | V |
| Gate-Source Leakage | I _{GSS} | V _{DS} = | $V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$ | | - | ± 100 | nA |
| | | $V_{GS} = 0 V$ | V _{DS} = -100 V | - | - | -1 | |
| Zero Gate Voltage Drain Current | I _{DSS} | $V_{GS} = 0 V$ | V _{DS} = -100 V, T _J = 125 °C | - | - | -50 | μΑ |
| | | $V_{GS} = 0 V$ | V _{DS} = -100 V, T _J = 175 °C | - | - | -250 | |
| On-State Drain Current ^a | I _{D(on)} | V _{GS} = -10 V | V _{DS} ≤ -5 V | -93 | - | - | Α |
| | | V _{GS} = -10 V | I _D = -30 A | - | 0.0155 | 0.0190 | Ω |
| Drain Source On State Registance 8 | B | V _{GS} = -10 V | I _D = -30 A, T _J = 125 °C | - | - | 0.0342 | |
| Drain-Source On-State Resistance a | R _{DS(on)} | V _{GS} = -10 V | I _D = -30 A, T _J = 175 °C | - | - | 0.0432 | |
| | | V _{GS} = -4.5 V | I _D = -20 A | - | 0.0177 | 0.0222 | |
| Forward Transconductance b | 9fs | $V_{DS} = -15 \text{ V}, I_D = -30 \text{ A}$ | | - | 50 | - | S |
| Dynamic ^b | | | | | | | |
| Input Capacitance | C _{iss} | | | - | 10 800 | 14 100 | |
| Output Capacitance | Coss | $V_{GS} = 0 V$ | V _{DS} = -25 V, f = 1 MHz | - | 800 | 1100 | pF |
| Reverse Transfer Capacitance | C _{rss} | | | - | 650 | 850 | |
| Total Gate Charge ^c | Qg | | | - | 220 | 350 | |
| Gate-Source Charge ^c | Q _{gs} | $V_{GS} = -10 \text{ V}$ | $V_{DS} = -50 \text{ V}, I_D = -50 \text{ A}$ | - | 37 | - | nC |
| Gate-Drain Charge ^c | Q _{gd} | | | - | 51 | - | |
| Gate Resistance | R_g | | f = 1 MHz | | 2.2 | 3.5 | Ω |
| Turn-On Delay Time ^c | t _{d(on)} | | | | 20 | 30 | |
| Rise Time ^c | t _r | V_{DD} = -50 V, R_L = 1 Ω I_D \cong -50 A, V_{GEN} = -10 V, R_g = 1 Ω | | - | 21 | 35 | ns |
| Turn-Off Delay Time ^c | t _{d(off)} | | | - | 110 | 175 | |
| Fall Time ^c | t _f | | | - | 30 | 50 | |
| Source-Drain Diode Ratings and Chara | cteristics ^b | | | | | | |
| Pulsed Current ^a | I _{SM} | | | - | - | -200 | Α |
| Forward Voltage | V _{SD} | I _F = -70 A, V _{GS} = 0 V | | | -0.885 | -1.5 | V |

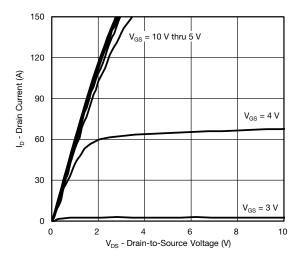
Notes

- a. Pulse test; pulse width $\leq 300~\mu s,\,duty~cycle \leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

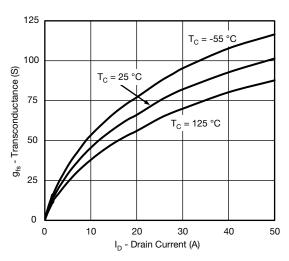
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



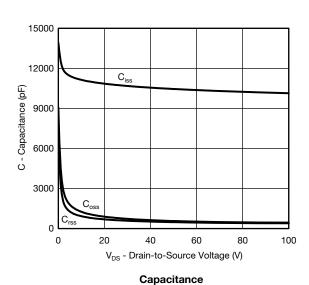
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)

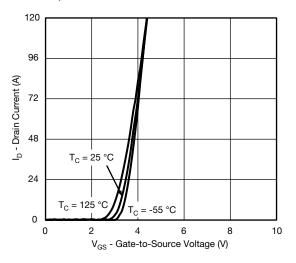


Output Characteristics

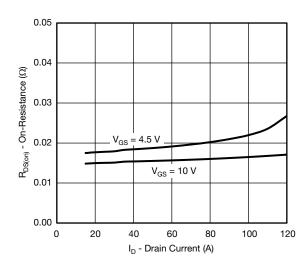


Transconductance

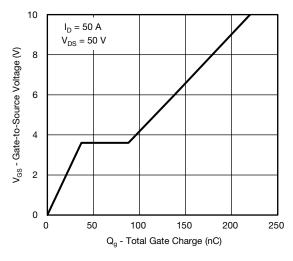




Transfer Characteristics

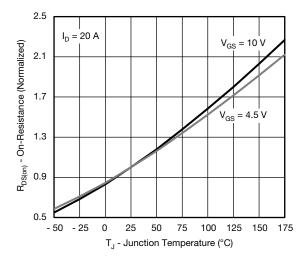


On-Resistance vs. Drain Current

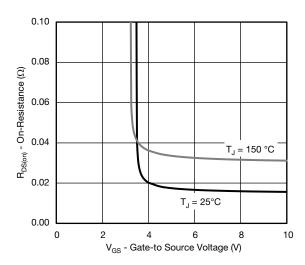




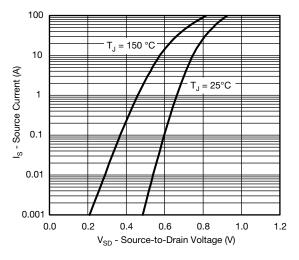
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



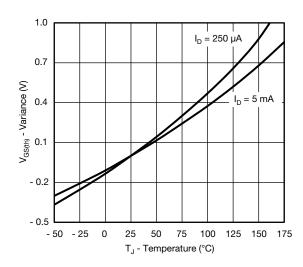
On-Resistance vs. Junction Temperature



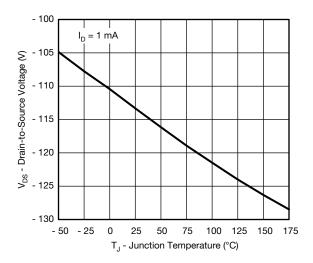
On-Resistance vs. Gate-to-Source Voltage



Source Drain Diode Forward Voltage



Threshold Voltage

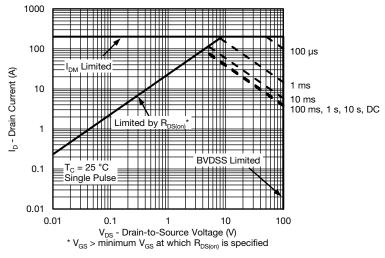


Drain Source Breakdown vs. Junction Temperature

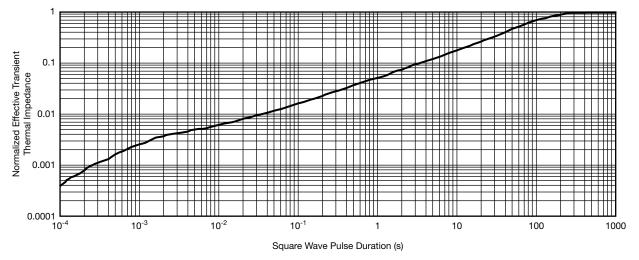
For technical questions, contact: automostech



THERMAL RATINGS ($T_A = 25$ °C, unless otherwise noted)



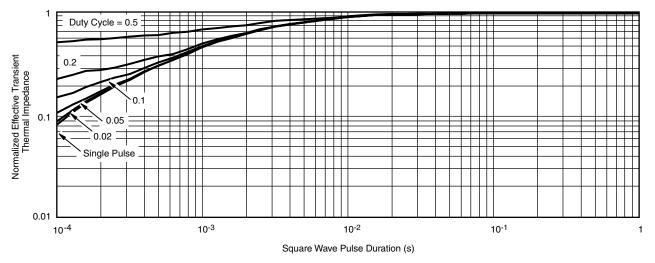
Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Ambient



THERMAL RATINGS (T_A = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case

Note

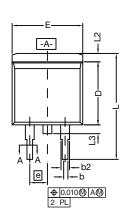
- The characteristics shown in the two graphs
 - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
 - Normalized Transient Thermal Impedance Junction-to-Case (25 °C)

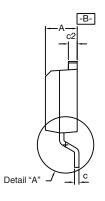
are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

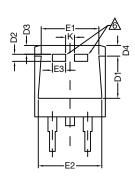
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TO-263 (D²PAK): 3-LEAD

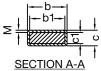








DETAIL A (ROTATED 90°)



| _ - b1 , , , | |
|---|--------|
| ≥ | - - |

- 1. Plane B includes maximum features of heat sink tab and plastic.
- 2. No more than 25 % of L1 can fall above seating plane by max. 8 mils.
- 3. Pin-to-pin coplanarity max. 4 mils.
- 4. *: Thin lead is for SUB, SYB. Thick lead is for SUM, SYM, SQM.
- 5. Use inches as the primary measurement.

6. This feature is for thick lead.

| INC | | HES | MILLIMETERS | | | |
|---------------------------------|------------|-------|-------------|-----------|--------|--|
| DIM. | | MIN. | MAX. | MIN. | MAX. | |
| Α | | 0.160 | 0.190 | 4.064 | 4.826 | |
| | b | 0.020 | 0.039 | 0.508 | 0.990 | |
| | b1 | 0.020 | 0.035 | 0.508 | 0.889 | |
| | b2 | 0.045 | 0.055 | 1.143 | 1.397 | |
| c* | Thin lead | 0.013 | 0.018 | 0.330 | 0.457 | |
| C | Thick lead | 0.023 | 0.028 | 0.584 | 0.711 | |
| c1 | Thin lead | 0.013 | 0.017 | 0.330 | 0.431 | |
| CI | Thick lead | 0.023 | 0.027 | 0.584 | 0.685 | |
| | c2 | 0.045 | 0.055 | 1.143 | 1.397 | |
| | D | 0.340 | 0.380 | 8.636 | 9.652 | |
| | D1 | 0.220 | 0.240 | 5.588 | 6.096 | |
| D2 | | 0.038 | 0.042 | 0.965 | 1.067 | |
| D3 | | 0.045 | 0.055 | 1.143 | 1.397 | |
| | D4 | 0.044 | 0.052 | 1.118 | 1.321 | |
| E | | 0.380 | 0.410 | 9.652 | 10.414 | |
| | E1 | 0.245 | 45 - 6.223 | | = | |
| | E2 | 0.355 | 0.375 | 9.017 | 9.525 | |
| | E3 | 0.072 | 0.078 | 1.829 | 1.981 | |
| е | | 0.100 |) BSC | 2.54 BSC | | |
| K | | 0.045 | 0.055 | 1.143 | 1.397 | |
| L | | 0.575 | 0.625 | 14.605 | 15.875 | |
| L1 | | 0.090 | 0.110 | 2.286 | 2.794 | |
| L2 | | 0.040 | 0.055 | 1.016 | 1.397 | |
| L3 | | 0.050 | 0.070 | 1.270 | 1.778 | |
| | L4 | 0.010 |) BSC | 0.254 BSC | | |
| | М | - | 0.002 | - | 0.050 | |
| ECN: T13-0707-Rev. K, 30-Sep-13 | | | | | | |

DWG: 5843





RECOMMENDED MINIMUM PADS FOR D²PAK: 3-Lead



Recommended Minimum Pads Dimensions in Inches/(mm)

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